Silicon N Channel MOS Type / Silicon Epitaxial Schottky Barrier Diode

# SSM5H06FE

#### **DC-DC Converter**

- Combined Nch MOSFET and Schottky Diode in one Package.
- Small package

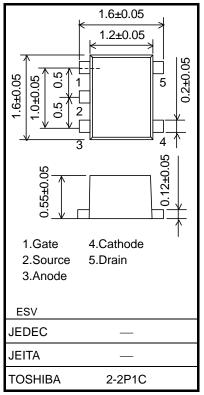
**DIODE COMMON** 

#### Absolute Maximum Ratings (Ta = 25°C) MOSFET

Characteristics		Symbol	Rating	Unit	
Drain-Source voltage		V <sub>DS</sub>	20	V	
Gate-Source voltage		V <sub>GSS</sub>	±10	V	
Drain current	DC	I <sub>D</sub>	100	mA	
	Pulse	I <sub>DP</sub> (Note 2)	200	ША	
Drain power dissipation		P <sub>D</sub> (Note 1)	150	mW	
Channel temperature		T <sub>ch</sub>	150	°C	

#### Absolute Maximum Ratings (Ta = 25°C) SCHOTTKY DIODE

Characteristics	Symbol	Rating	Unit
Maximum (peak) reverse voltage	V <sub>RM</sub>	15	V
Reverse voltage	VR	12	V
Average forward current	Ι <sub>Ο</sub>	100	mA
Peak one cycle surge forward current (non-repetitive)	I <sub>FSM</sub>	1 (50 Hz)	А
Junction temperature	Тј	125	°C



## Absolute Maximum Ratings (Ta = 25°C) MOSFET,

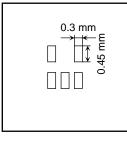
Weight:	3	mg	(typ.)
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Characteristics	Symbol	Rating	Unit
Storage temperature	T <sub>stg</sub>	-55~125	°C
Operating temperature	T <sub>opr</sub> (Note 3)	-40~100	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### Note 1: Mounted on FR4 board (25.4 mm $\times$ 25.4 mm $\times$ 1.6 t, Cu Pad: 0.135 mm<sup>2</sup> $\times$ 5)



Note 2: The pulse width limited by max channel temperature.

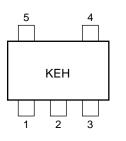
Note 3: Operating temperature limited by max channel temperature and max junction temperature.

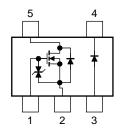
Unit: mm

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#### Marking

#### **Equivalent Circuit**





#### **Handling Precaution**

When handling individual devices (which are not yet mounted on a circuit board), be sure that the environment is protected against electrostatic discharge. Operators should wear anti-static clothing, and containers and other objects that come into direct contact with devices should be made of anti-static materials.

The Channel-to-Ambient thermal resistance  $R_{th (ch-a)}$  and the drain power dissipation  $P_D$  vary according to the board material, board area, board thickness and pad area. When using this device, please take heat dissipation fully into account.

#### MOSFET

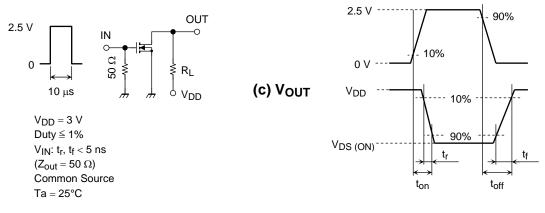
#### **Electrical Characteristics (Ta = 25°C)**

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I <sub>GSS</sub>	$V_{GS}=\pm 10~V,~V_{DS}=0$	—	—	±1	μΑ
Drain-Source bre	akdown voltage	V (BR) DSS	$I_D = 0.1 \text{ mA}, V_{GS} = 0$	20	_		V
Drain cut-off current		IDSS	$V_{DS} = 20 V, V_{GS} = 0$	_	_	1	μΑ
Gate threshold voltage		V <sub>th</sub>	$V_{DS} = 3 \text{ V}, \text{ I}_{D} = 0.1 \text{ mA}$	0.6	_	1.1	V
Forward transfer admittance		Y <sub>fs</sub>	$V_{DS} = 3 \text{ V}, \text{ I}_{D} = 10 \text{ mA}$	40	_		mS
Drain-Source on-resistance		R <sub>DS</sub> (ON)	$I_D = 10 \text{ mA}, V_{GS} = 4 \text{ V}$	_	1.5	3.0	Ω
			$I_D = 10 \text{ mA}, V_{GS} = 2.5 \text{ V}$	_	2.2	4.0	
			$I_D = 1 \text{ mA}, V_{GS} = 1.5 \text{ V}$	_	5.2	15	
Input capacitance		C <sub>iss</sub>	$V_{DS} = 3 V, V_{GS} = 0, f = 1 MHz$	_	9.3		pF
Reverse transfer capacitance		C <sub>rss</sub>	$V_{DS} = 3 V, V_{GS} = 0, f = 1 MHz$	_	4.5		pF
Output capacitance		C <sub>oss</sub>	$V_{DS} = 3 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$	—	9.8	—	pF
Switching time	Turn-on time	t <sub>on</sub>	$V_{DD} = 3 V, I_D = 10 mA, V_{GS} = 0-2.5 V$	_	70		20
	Turn-off time	t <sub>off</sub>			125	_	ns

#### **Switching Time Test Circuit**

#### (a) Test circuit

(b) V<sub>IN</sub>



#### Precaution

 $V_{th}$  can be expressed as voltage between gate and source when the low operating current value is I\_D  $\,$  100  $\mu A$  for this product. For normal switching operation, V\_GS (on) requires a higher voltage than V\_{th} and V\_GS (off) requires a lower voltage than V\_{th}.

(The relationship can be established as follows:  $V_{GS (off)} < V_{th} < V_{GS (on)}$ ) Please take this into consideration when using the device.

#### Schottky Diode

#### **Electrical Characteristics** (Ta = 25°C)

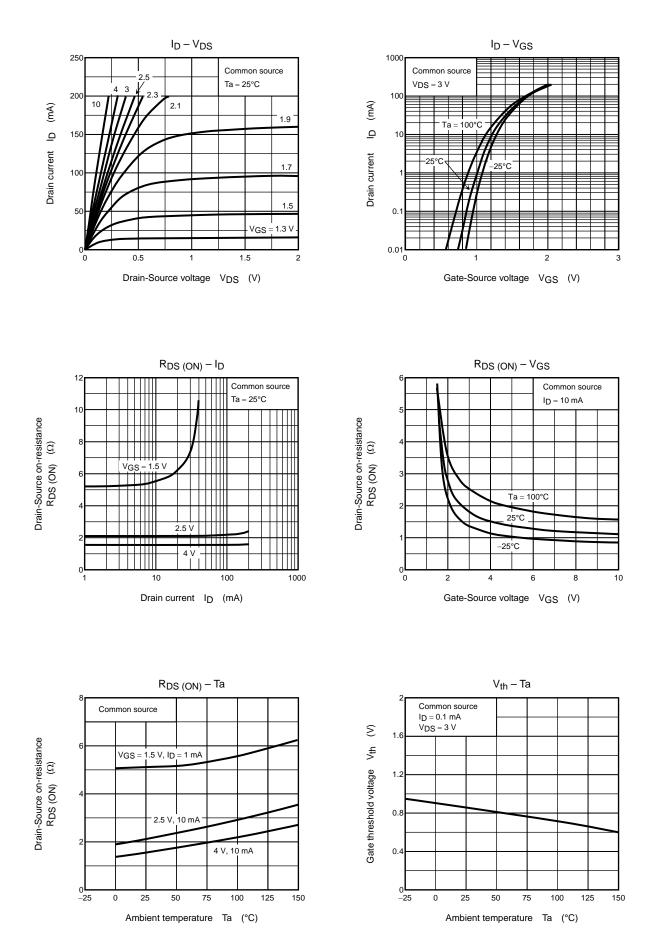
Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward voltage	V <sub>F (1)</sub>	I <sub>F</sub> = 1mA	_	0.18	_	V
	V <sub>F (2)</sub>	I <sub>F</sub> = 5mA		0.23	0.30	V
	V <sub>F (3)</sub>	I <sub>F</sub> = 100mA	_	0.35	0.50	V
Reverse current	I <sub>R</sub>	V <sub>R</sub> = 12 V	_	_	22	μΑ
Total capacitance	CT	V <sub>R</sub> = 0 V, f = 1 MHz		20	40	pF

#### Precaution

The schottky barrier diodes of this product have large-reverse-current-leakage characteristics compared to other switching diodes. This current leakage and improper operating temperature or voltage may cause thermal runaway resulting in breakdown. Take forward and reverse loss into consideration in radiation design and safety design.

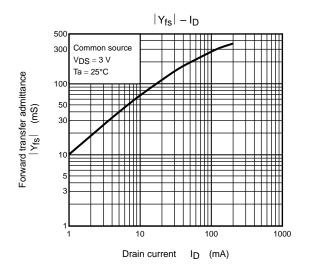
#### **MOSFET Electrical Characteristics Graph**

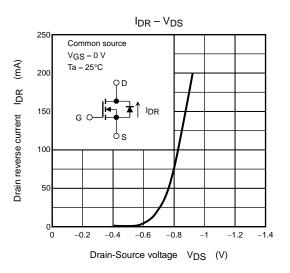
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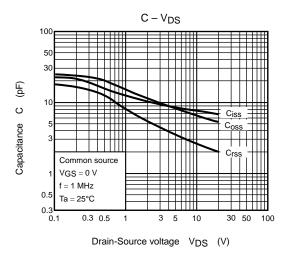


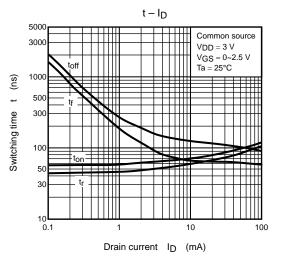
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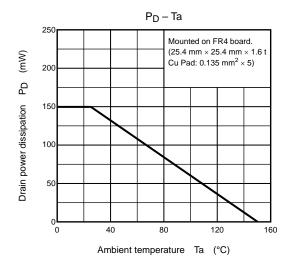
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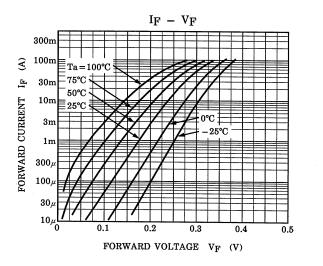


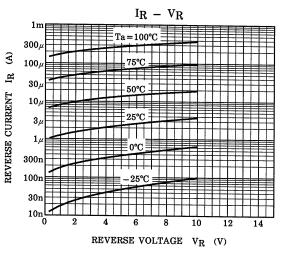


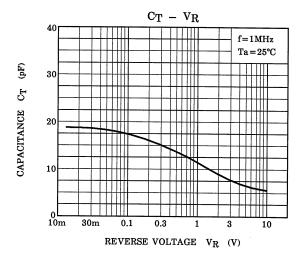




### SBD Electrical Characteristics Graph







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